

MT18Ex(C)

- MicroThin为附18 μm 载体铜箔的超薄铜箔。
MicroThin is ultra thin foil with 18 μm carrier foil.
- 最适用于线宽/线距(L/S)=20/20~35/35之应用。
Usable for fine pitch pattern L/S=20/20 - 35/35 formation.
- 适用于无芯封装基板的工艺。
Suitable for core-less process

用途/Application

- IC封装基板
/Semiconductor Package
- 无芯封装基板
/Core-less substrate

构成/Composition



生产地点/Production Site

- 日本 / Japan

代表性特性数据/Representative data

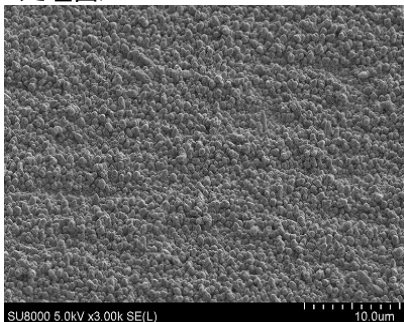
	μm	Area weight (g/m ²)	Laminate side Rz(μm)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm) ^{@FR-4}
MT18Ex(C)	2	24	2	-	-	1.2
	3	33	2	-	-	1.2
	5	51	2	-	-	1.2

※上述表列为代表性数据非保证值

This is representative data, not guaranteed.

※Peel Strength为增镀到35 μm 厚度之后的测试值
Evaluated after plated up to 35 μm .

处理面/Laminate side



阻剂面/ resist side

